

RELIABILITY REPORT  
FOR  
MAX6420UK29+  
PLASTIC ENCAPSULATED DEVICES

October 15, 2010

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

<b>Approved by</b>
Don Lipps
Quality Assurance
Manager, Reliability Engineering

## Conclusion

The MAX6420UK29+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

## Table of Contents

<b>I. ....Device Description</b>	<b>V. ....Quality Assurance Information</b>
<b>II. ....Manufacturing Information</b>	<b>VI. ....Reliability Evaluation</b>
<b>III. ....Packaging Information</b>	<b>IV. ....Die Information</b>
<b>.....Attachments</b>	

### I. Device Description

#### A. General

The MAX6412-MAX6420 low-power microprocessor supervisor circuits monitor system voltages from 1.6V to 5V. These devices are designed to assert a reset signal whenever the VCC supply voltage or RESET IN falls below its reset threshold or the manual reset input is asserted. The reset output remains asserted for the reset timeout period after VCC and RESET IN rise above the reset threshold and the manual reset input is deasserted. The reset timeout is externally set by a capacitor to provide more flexibility. The MAX6412/MAX6413/MAX6414 feature fixed thresholds from 1.575V to 5V in approximately 100mV increments and a manual reset input. The MAX6415/MAX6416/MAX6417 are offered with an adjustable reset input that can monitor voltages down to 1.26V and the MAX6418/MAX6419/MAX6420 are offered with one fixed input and one adjustable input to monitor dual-voltage systems. The MAX6412/MAX6415/MAX6418 have an active-low, push-pull reset output. The MAX6413/MAX6416/MAX6419 have an active-high, push-pull reset output and the MAX6414/MAX6417/MAX6420 have an active-low, open-drain reset output. All of these devices are offered in a SOT23-5 package and are fully specified from -40°C to +125°C.

## II. Manufacturing Information

A. Description/Function:	Low-Power, Single/Dual-Voltage $\mu$ P Reset Circuits with Capacitor-Adjustable Reset Timeout Delay
B. Process:	B8
C. Number of Device Transistors:	292
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	January 26, 2002

## III. Packaging Information

A. Package Type:	5-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0178
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	324.3°C/W
K. Single Layer Theta Jc:	82°C/W
L. Multi Layer Theta Ja:	N/A
M. Multi Layer Theta Jc:	N/A

## IV. Die Information

A. Dimensions:	36 X 36 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

**V. Quality Assurance Information**

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

**VI. Reliability Evaluation**

## A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 90 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 12.2 \times 10^{-9}$$

$\lambda = 12.2$  F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

## B. E.S.D. and Latch-Up Testing (lot I8K8BQ001B, D/C 0329)

The MS60-8 die type has been found to have all pins able to withstand a HBM transient pulse of +/-800V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-50mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX6420UK29+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C	DC Parameters	45	0	S8K0CQ001B, DC 0341
	Biased	& functionality	45	0	I8K0BQ001B, DC 0234
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.